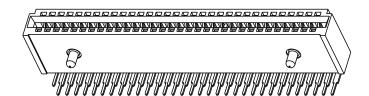
				_		
PRODUCT NO.	POSITION	REMARK	DIM "C"	DIM "D"	DIM "E"	
10053363-100LF	2 X 3 2	WITH KEY	54.61	54.46	3.50±0.25	
10053363-200LF	2 X 3 2	WITHOUT KEY	N/A	N/A	3.50±0.25	
10053363-201LF	2 X 3 2	WITHOUT KEY	N/A	N / A	2.60±0.10	

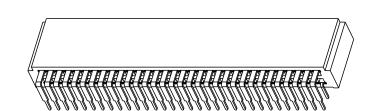
NOTES:

I. MATERIALS: HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0 RATED, BLACK. TERMINAL: HIGH CONDUCTIVITY COPPER ALLOY.

CONTACT AREA: 30u" GOLD OVER 50u" NICKEL UNDERPLATED. SOLDER TAIL: 100u" TIN OVER 50u" NICKEL UNDERPLATED.

- 2. PRODUCT PERFORMANCE SPEC. PER GS-12-259.
- 3. PACKAGE SPECIFICATION PER GS-14-937.
- 4. PART NUMBER 10053363-X00LF MEETS EUROPEAN UNION DIRECTIVE AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C PEAK TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDER APPLICATION WITH A CIRCUIT BOARD.
- 5. MANUFACTURER'S NAME, P/N AND DATE CODE TO APPEAR ON THIS SURFACE AS PER GS-24-007.







C

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D

Pro/E File - REV C - 2009-06-09

spec ref	*		dr	wcadmin		2006/08/07	proj	ection	1 1	١./	s i z e	scale		
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED		eng	Wei-Long Zhang	J	2012/06/06		\leftarrow	MM		A 4	1.000		
			chr	-		-					ecn no	ELX-DG-01184	340-1	
			appr	Pei-Ming Zheng		2012/06/06	product	family	•		rel level	Releas	sed	
surface /	0.X 0.XX 0.XXX	0.X	±0.30			L ° 2X32P RIGHT		. ANGLE			0 4		r	rev
		±0.15	, FSh 🗄	<u> </u>	- ZNJZI NIOIII ANOL		- L	0	1005336	3				
		0.XXX	±0.08	"	+ POW	VER CARD EDGE			× ∞				K	
	angular	0°	±2°	www.	fci.com	cat, no	٥.	*	Pr	oduct -	Customer	Drw	sheet Lof 3	3

3

STATUS:Released

PDS: Rev:K

Printed: Jun 06, 2012

